

IN THE SPECIFICATION

Please insert the following sentence at page 14, between line 17 and line 18.

--FIG. 7 is a block diagram of a mask writing tool used in this invention.--

Please insert the following paragraph at page 24, between line 13 and 14.

-- In the first and second embodiments, there is provided a mask writing tool 70 (an apparatus for forming a pattern for a semiconductor device), as shown in FIG. 7, which comprises a beam shaping unit 72 for shaping, to a predetermined shape, one of a charged particle beam and an electromagnetic beam, a positioning unit 74 for positioning the position of the beam of the predetermined shape in a single unit region of a substrate with a photosensitive film formed thereon, and a shot exposure unit 76 for radiating the single unit region with the beam for a predetermined period of time. The shot exposure unit 76 repeats shot exposure in units of a single unit region to thereby form a desired exposed region, and the positioning unit 74 sequentially forwards the position in which the beam is to be radiated, butt-joins the single unit region to another single unit region to form a plurality of butt-unit regions, and situates butting portions of the butt-jointed unit regions constituting the desired exposed portion, in a first area of a layer to be formed other than a second area of the first layer in which predetermined characteristics of a function of the semiconductor device are determined by a pattern width of the exposed region in association with another pattern formed in another layer.--

Please insert the following paragraph at page 31, between line 22 and line 23.

--In the third and fourth embodiments, there is provided a mask writing tool 70 (an apparatus for forming a pattern for a semiconductor device), as shown in FIG. 7, which comprises a beam shaping unit 72 for shaping, to a predetermined shape, one of a charged particle beam and an electromagnetic beam, a positioning unit 74 for positioning the position of the beam of the predetermined shape in a single unit region of a substrate with a

photosensitive film formed thereon, and a shot exposure unit 76 for radiating the single unit region with the beam for a predetermined period of time. The shot exposure unit 76 subjects predetermined ones of the unit regions to single shot exposure, and the other ones of the unit regions to multiple shot exposure, and the positioning unit 74 sequentially forwards the position in which the beam is to be radiated, and butt-joins the single region to another single unit region to form a plurality of butt-joined unit regions.--